

PTDHA75120NY

1200V 75A Si IGBT Discrete

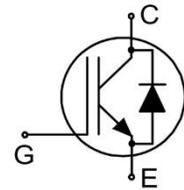
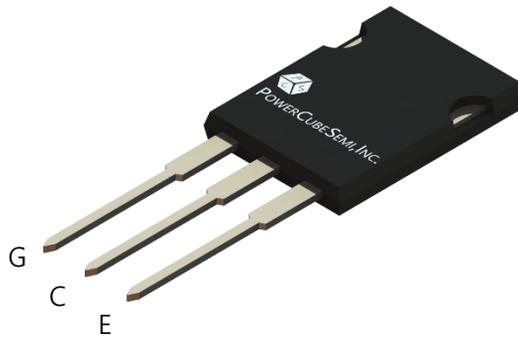
Features

Si IGBT Discrete

- Rated to 1200V at 75Amps @ $T_C = 100^\circ\text{C}$
- $V_{CE(sat)} = 2.10\text{V}$ @ $I_C = 75\text{A}$
- High breakdown voltage to 1200V for improved reliability
- Maximum Junction Temperature 175°C
- Positive temperature coefficient
- Including fast & soft recovery anti-parallel FWD

Application

- Inverter for motor drive
- Three-level solar string inverter
- Uninterruptible power supply



PKG type : TO-247 Plus



Absolute Maximum Ratings

Symbol	Parameter	Value	Unit	
BV_{CES}	Collector-Emitter Breakdown Voltage	1200	V	
I_C	DC Collector Current	$T_C = 25^\circ\text{C}$	150	A
		$T_C = 100^\circ\text{C}$	75	
$I_{C, Pulse}$	Pulsed Collector Current	300	A	
I_F	Diode Forward Current	$T_C = 25^\circ\text{C}$	120	A
		$T_C = 100^\circ\text{C}$	75	
$I_{F, Pulse}$	Diode Pulsed Current	300	A	
V_{GE}	Continuous Gate-Emitter Voltage	± 20	V	
V_{GE}	Transient Gate-Emitter Voltage	± 30		
P_D	Power Dissipation	$T_C = 25^\circ\text{C}$	600	W
t_{SC}	Short circuit withstand time	10	μs	
T_{vj}	Operating Junction Temperature Range	-40 to 175	$^\circ\text{C}$	
T_{stg}	Storage Temperature Range	-55 to 175		

Package Marking and Ordering Information

Device Marking	Device	Package	Packing Method	Tape width	Quantity
PTDHA75120NY	PTDHA75120	TO-247 plus	TUBE	-	30

Electrical Characteristics $T_j=25^\circ\text{C}$ Unless Otherwise Specified

Static Characteristics

Symbol	Parameter	Test Condition	Numerical			Unit	
			Min	Typ	Max		
BV_{CES}	Collector-Emitter Breakdown Voltage	$I_C=250\mu\text{A}$, $V_{GE}=0\text{V}$	1200	-	-	V	
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C=75\text{A}$, $V_{GE}=15\text{V}$	$T_j=25^\circ\text{C}$	1.80	2.10	2.50	V
			$T_j=125^\circ\text{C}$	-	2.50	-	
			$T_j=150^\circ\text{C}$	-	2.60	-	
$V_{GE(TH)}$	Gate-Emitter Threshold Voltage	$V_{CE}=V_{GE}$, $I_C=2.6\text{mA}$	5.2	5.8	6.5	V	
I_{CES}	Zero Gate Voltage Collector Current	$V_{CE}=1200\text{V}$, $V_{GE}=0\text{V}$	$T_j=25^\circ\text{C}$	-	-	0.25	mA
			$T_j=150^\circ\text{C}$	-	-	5.00	
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=\pm 20\text{V}$, $V_{CE}=0\text{V}$	-	-	100	nA	

Dynamic Characteristics

Symbol	Parameter	Test Condition	Numerical			Unit	
			Min	Typ	Max		
Q_G	Total Gate Charge	$V_{CC}=960\text{V}$, $I_C=75\text{A}$, $V_{GE}=15\text{V}$	-	0.65	-	μC	
V_F	Diode Forward Voltage	$I_F=75\text{A}$	$T_j=25^\circ\text{C}$	-	3.50	4.20	V
			$T_j=125^\circ\text{C}$	-	3.00	-	
			$T_j=150^\circ\text{C}$	-	2.80	-	
C_{IES}	Input Capacitance	$V_{CE}=25\text{V}$, $V_{GE}=0\text{V}$, $f=1\text{MHz}$	-	8.43	-	nF	
C_{RES}	Reverse Transfer Capacitance		-	0.19	-		



Electrical Characteristics

Switching Characteristics

Symbol	Parameter	Test Condition		Numerical			Unit
				Min	Typ	Max	
$t_{d(on)}$	Turn-On Delay Time	$V_{GE} = -5 \sim 15V,$ $V_{CC} = 600V,$ $I_C = 75A, R_G = 10\Omega$	$T_j = 25^\circ C$ $T_j = 125^\circ C$ $T_j = 150^\circ C$	-	30	-	ns
t_r	Turn-On Rise Time			-	28	-	
				-	26	-	
$t_{d(off)}$	Turn-Off Delay Time			-	227	-	mJ
				-	243	-	
-	252			-			
t_f	Turn-Off Fall Time			-	91	-	mJ
		-	108	-			
-	116	-					
E_{on}	Turn-On Switching Energy	-	8.5	-	mJ		
E_{off}	Turn-Off Switching Energy	-	8.7	-			
		-	8.8	-			
E_{rec}	Reverse Recovery Energy	-	1.35	-	mJ		
I_{rr}	Reverse Recovery Current	-	2.92	-			
		-	3.28	-			
Q_{rr}	Reverse Recovery Charge	$I_F = 75A, V_R = 600V,$ $di/dt = -500A/\mu s$	$T_j = 25^\circ C$ $T_j = 125^\circ C$ $T_j = 150^\circ C$	-	11	-	A
				-	15	-	
-	16			-			
T_{rr}	Reverse Recovery Time			-	3.01	-	uC
				-	6.74	-	
-	8.47			-			
T_{rr}	Reverse Recovery Time			-	189	-	ns
		-	235	-			
-	278	-					

Thermal Characteristics

Symbol	Parameter	Numerical	Unit
$R_{\theta(J-A)}$	Thermal Resistance Junction-to-Ambient	40	K/W
$R_{\theta(J-C)}$	Thermal Resistance Junction-to-Case for IGBT	0.25	
$R_{\theta(J-C)}$	Thermal Resistance Junction-to-Case for Diode	0.35	

Typical Characteristics

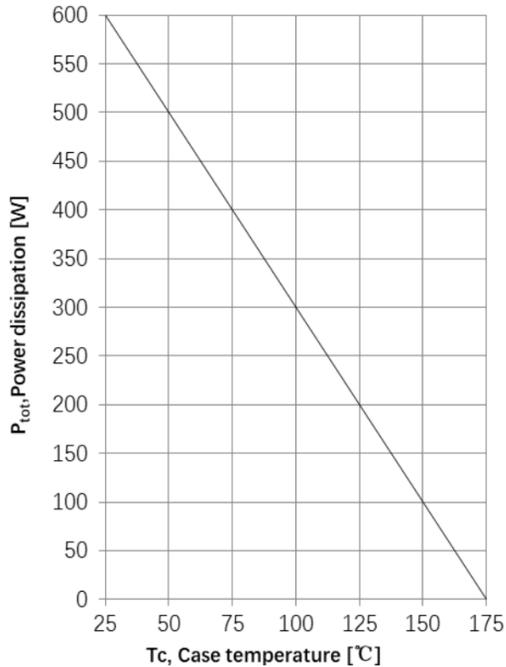


Figure 1. Power dissipation as a function of case temperature ($T_J \leq 175^\circ\text{C}$)

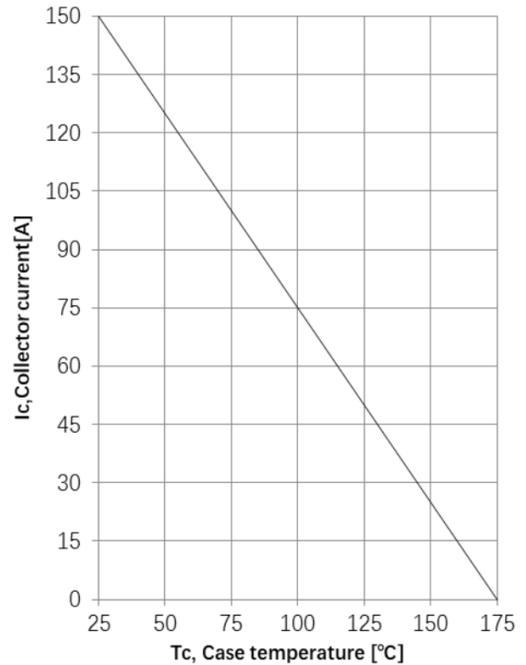


Figure 2. Collector current as a function of case temperature ($V_{GE} \geq 15\text{V}$, $T_J \leq 175^\circ\text{C}$)

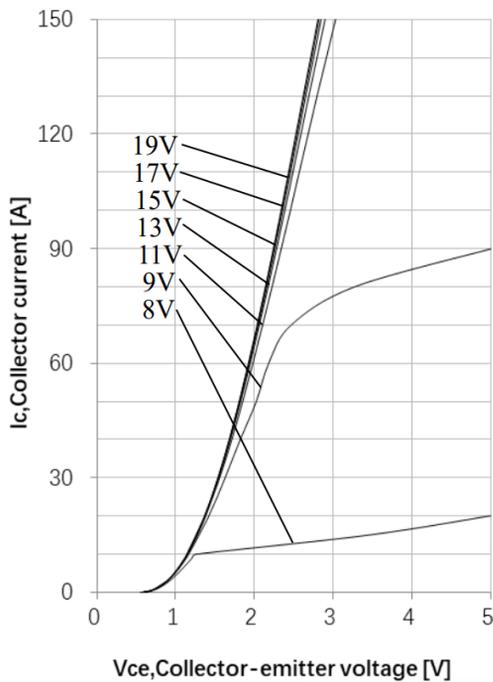


Figure 3. Output Characteristics ($T_J = 25^\circ\text{C}$)

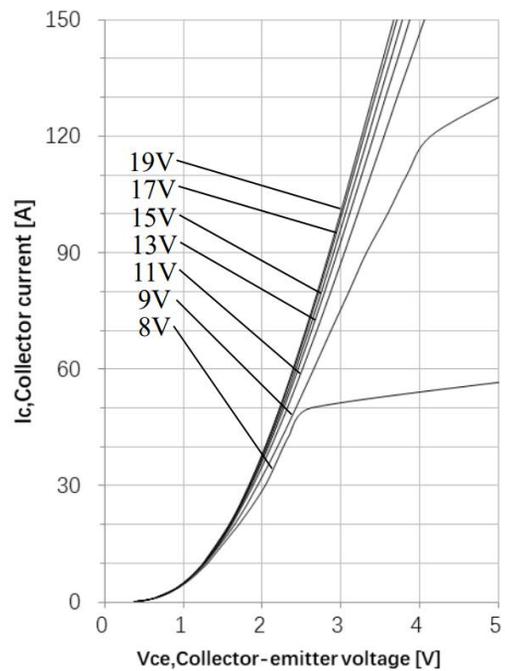


Figure 4. Output Characteristics ($T_J = 150^\circ\text{C}$)

Typical Characteristics

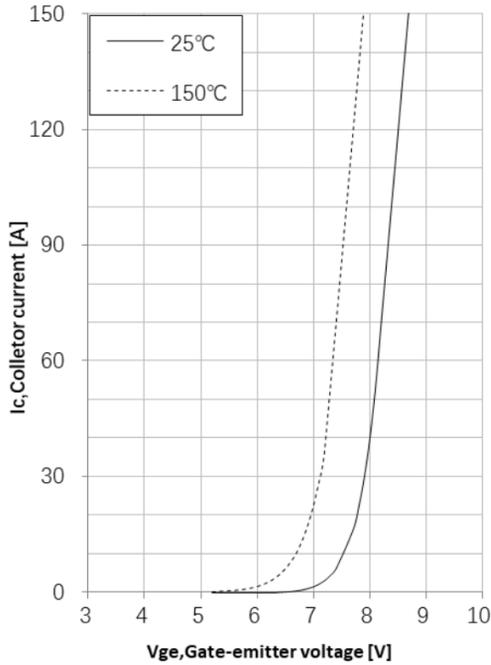


Figure 5. Typical transfer characteristic ($V_{CE}=20V$)

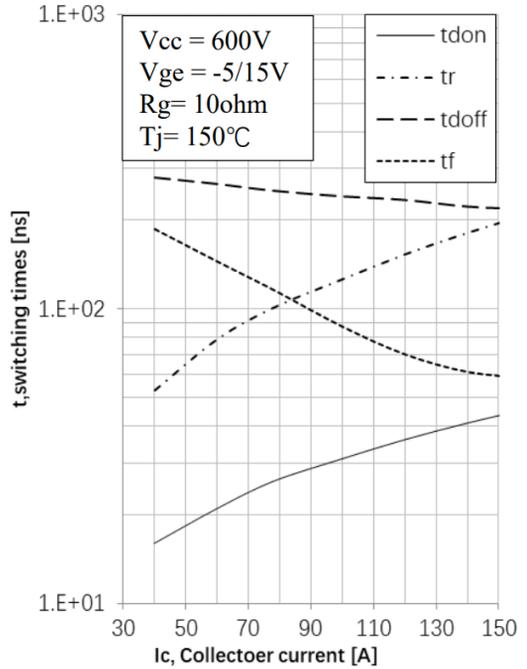


Figure 6. Typical Switching time as a function of collector current

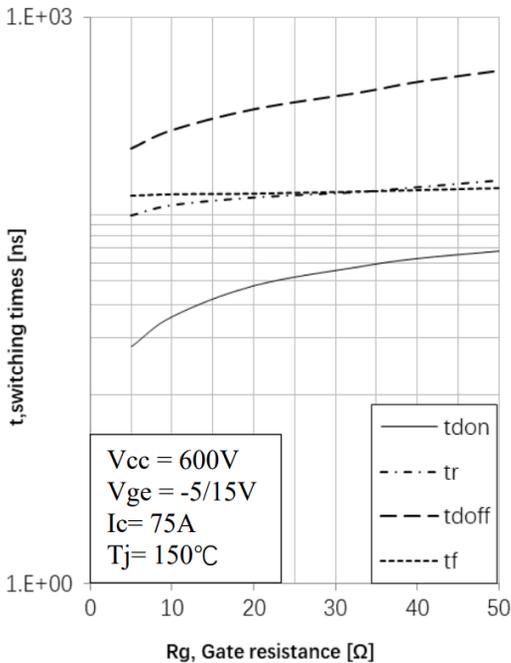


Figure 7. Typical Switching times as a function of gate resistance

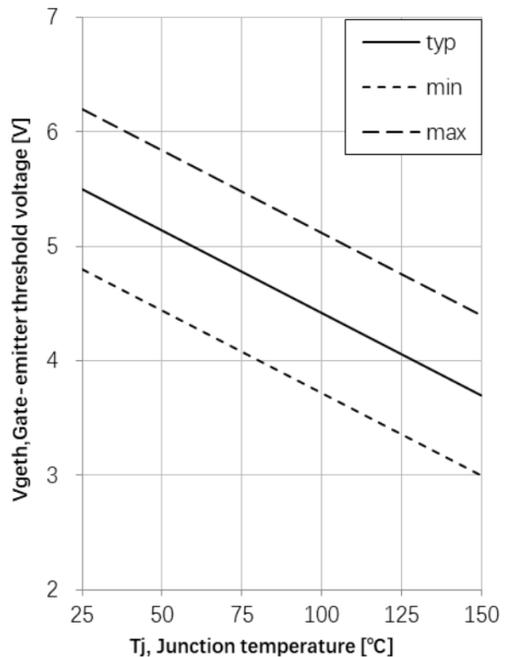


Figure 8. Gate-Emitter threshold voltage as a function of junction temperature

Typical Characteristics

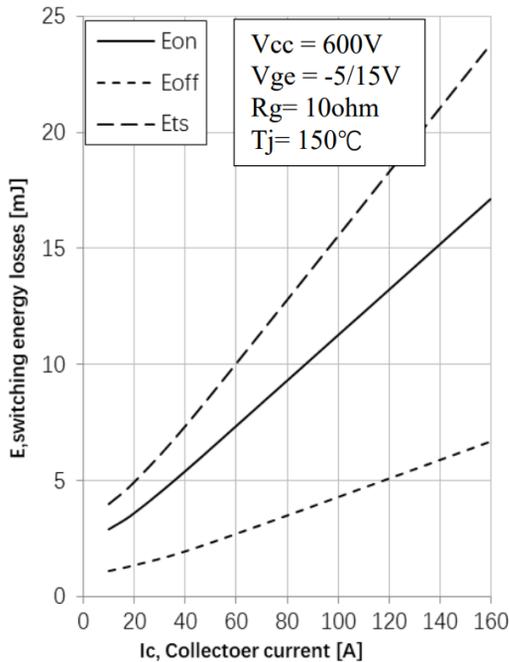


Figure 9. Typical Switching energy losses as a function of collector current

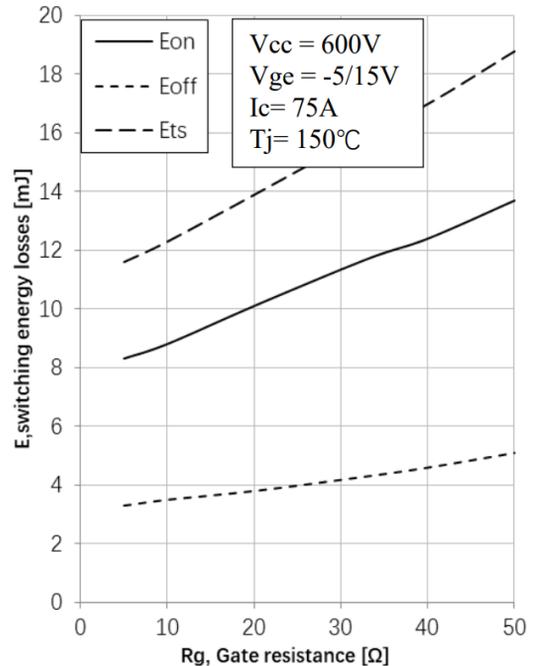


Figure 10. Typical Switching energy losses as a function of gate resistance

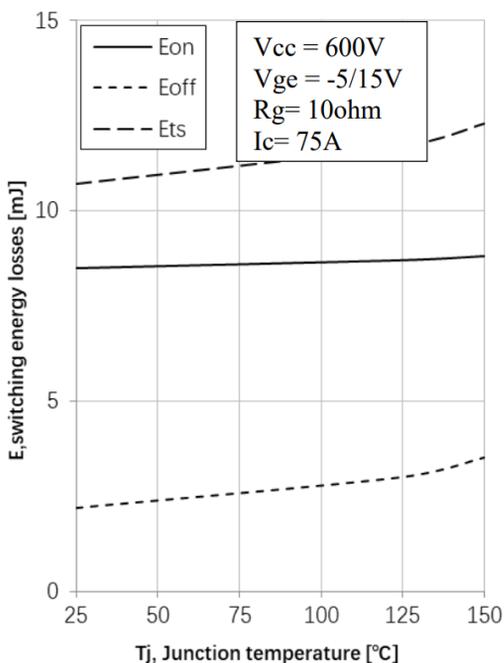


Figure 11. Typical Switching Energy losses as a function of junction temperature

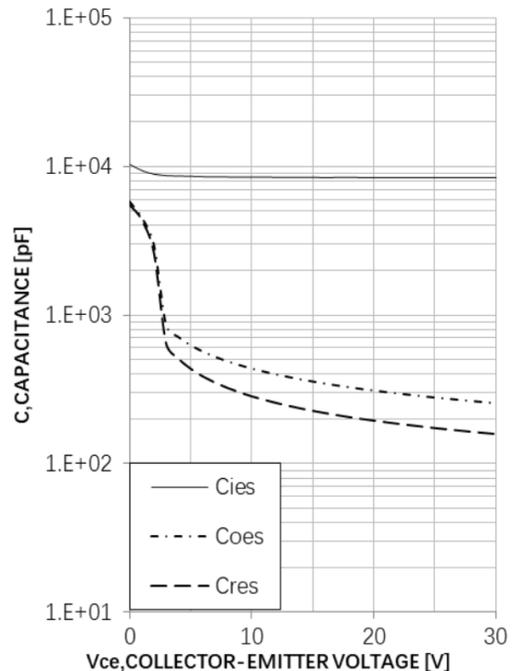


Figure 12. Typical capacitance as a function of collector-emitter voltage

Typical Characteristics

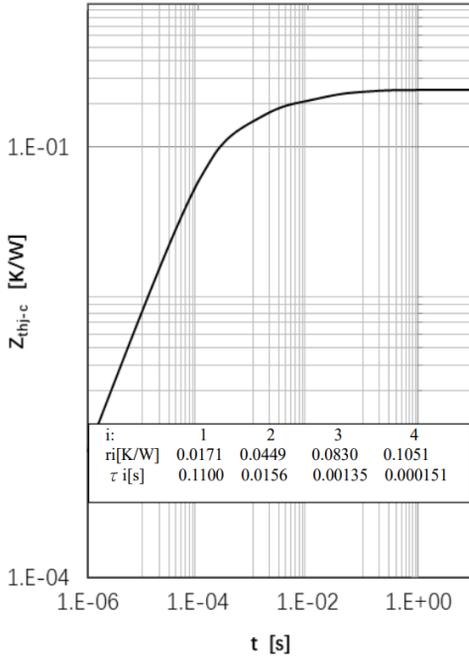


Figure 13. IGBT Transient Thermal Impedance

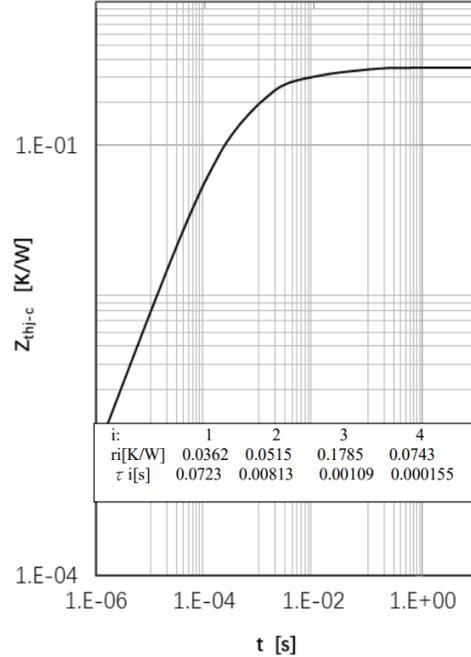


Figure 14. Diode Transient Thermal Impedance

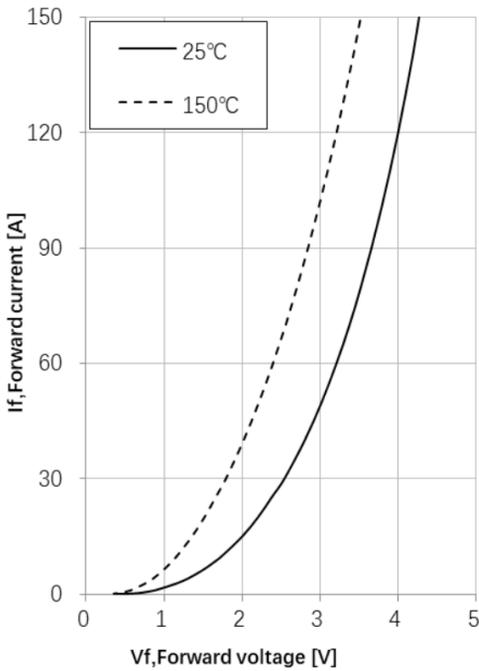
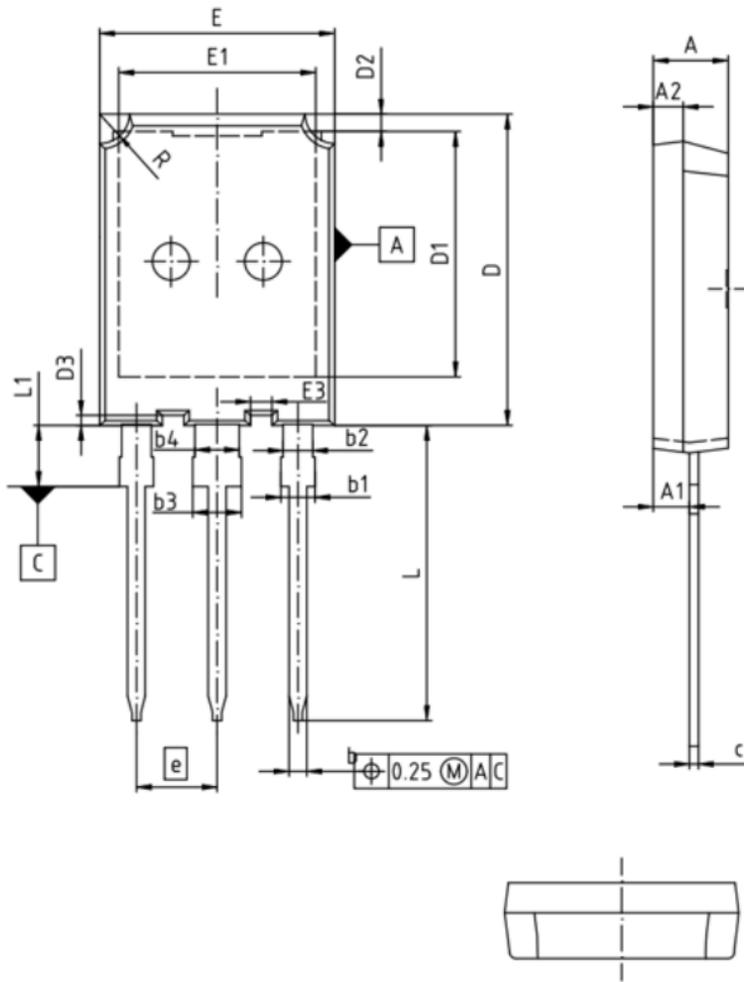


Figure 15. Diode forward current as a function of forward voltage

Package Outline

Unit : mm



SYMBOL	DIMENSIONS	
	MIN	MAX
A	4.90	5.10
A1	2.31	2.51
A2	1.90	2.10
b	1.16	1.26
b1	1.86	2.16
b2	1.96	2.06
c	0.58	0.64
D	20.90	21.10
D1	16.25	16.85
D2	1.05	1.35
D3	0.58	0.78
E	15.70	15.90
E1	13.10	13.50
E3	1.35	1.55
e	5.44 BSC	
L	19.78	20.08
L1	4.03	4.23
R	1.90	2.10